

TMS570LS31x Hercules Development Kit (HDK)

User's Guide



Literature Number: SPNU509C
September 2011–Revised November 2018

Preface	4
1 Introduction	5
1.1 Scope of Document	5
1.2 TMS570LS31 HERCULES Development Kit (HDK) Features	5
1.3 HDK Board Block Diagram	6
1.4 TMS570LS31 HDK Contents	6
1.5 HDK Specifications	7
1.6 Basic Operation	7
1.7 Memory Map	7
1.8 Power Supply.....	8
2 Physical Description	9
2.1 Board Layout	9
2.2 Connectors	10
2.2.1 20-Pin ARM JTAG Header	11
2.2.2 Ethernet Interface	11
2.2.3 CAN Interface.....	11
2.2.4 J19, MIPI ETM Connector.....	12
2.2.5 J7, XDS100V2 USB JTAG Interface.....	13
2.2.6 P1, +5 V to +12 V Input	14
2.2.7 SCI Interface	14
2.2.8 Daughter Card Interface.....	14
2.3 LEDs	17
2.4 S2 DIP Switch	18
2.5 Jumpers	19
2.6 S4, Power On Reset Switch	19
2.7 S3, System Reset Switch	19
A Operation Notices	20
A.1 Operation Notices	20
Revision History	21

List of Figures

1-1.	TMS570LS31 HDK Board Block Diagram	6
2-1.	TMS570LS31 HDK Board, Interfaces Top Side	9
2-2.	Connectors on TMS570LS31 HDK	10
2-3.	CAN Bus Termination.....	12
2-4.	J2, J3 CAN Bus Interface (Screw Terminal)	12
2-5.	J19, 60 Pin MIPI ETM Header.....	12
2-6.	+12 V Input Jack	14
2-7.	J9, J10, and J11 on HDK	15
2-8.	DIP Switch Settings	18

List of Tables

1-1.	TMS570LS31 Memory Map	7
1-2.	Power Test Points	8
2-1.	Connectors on HDK Board.....	10
2-2.	20-Pin ARM JTAG Header	11
2-3.	J1, Ethernet Interface	11
2-4.	J19, MIPI Connector Signal Mapping.....	13
2-5.	J7, XDS100V2 USB JTAG Interface.....	13
2-6.	Expansion Connector P1 (J9, Left, BottomView)	15
2-7.	Expansion Connector P2 (J10, Right, BottomView)	16
2-8.	Expansion Connector P3 (J11, Bottom One, TopView).....	17
2-9.	Demo LEDs	18
2-10.	Other LEDs as Indicator	18
2-11.	S2 DIP Switch Functions	19
2-12.	Jumpers	19

Read This First

About This Manual

This document describes the board level operations of the TMS570LS31 Hercules™ Development Kit (HDK). The HDK is based on the Texas Instruments TMS570LS3137 Microcontroller. The TMS570LS31 HDK is a table top card that allows engineers and software developers to evaluate certain characteristics of the TMS570LS3137 microcontroller to determine if the microcontroller meets the designer's application requirements as well as begin early application development. Evaluators can create software to execute on board or expand the system in a variety of ways.

Notational Conventions

This document uses the following conventions.

The TMS570LS31 HDK will sometimes be referred to as the HDK.

Program listings, program examples, and interactive displays are shown in a special italic typeface. Here is a sample program listing:

- equations
- !rd = !strobe&rw

Information About Cautions

This book may contain cautions.

This is an example of a caution statement.

A caution statement describes a situation that could potentially damage your software, or hardware, or other equipment. The information in a caution is provided for your protection. Please read each caution carefully.

Related Documentation From Texas Instruments

Information regarding this device can be found at the following Texas Instruments website:
<http://www.ti.com/tms570>

⁽¹⁾ Hercules, Code Composer Studio are trademarks of Texas Instruments.
⁽²⁾ ARM is a registered trademark of ARM Limited.
⁽³⁾ All other trademarks are the property of their respective owners.

Introduction

This development kit provides a product-ready hardware and software platform for evaluating the functionality of the Texas Instruments TMS570LS31 microcontroller family. Schematics, list of materials, and PCB layout are available to ease hardware development and reduce time to market.

1.1 Scope of Document

This user's guide lists the contents of the development kit, points out the features of the major components, and provides the instructions necessary to verify your development kit is in working order. Any additional usage instructions or details fall outside the scope of this document. Additional resources will be listed at the end of this user's guide.

1.2 TMS570LS31 HERCULES Development Kit (HDK) Features

The HDK comes with a full complement of on board devices that suit a wide variety of application environments. Key features include:

- A Hercules TMS570LS3137 337-pin BGA microcontroller
- Integrated USB JTAG Emulator (XDS100v2)
- External JTAG Headers (ARM® 20 pin and TI Compact 20-pin CTI)
- 10/100 Mbps Ethernet interface
- Two CAN transceivers (SN65HVDA541Q1) and screw terminal blocks
- One ambient light sensor
- One ambient temperature sensor
- Microcontroller's serial communication interface (SCI) universal asynchronous receiver/transmitter (UART) accessible through a USB virtual COM port
- One 8MB SDRAM
- Eight user programmable white LEDs around the MCU silicon
- One user programmable pushbutton
- Three expansion connectors for hardware prototyping
- Reset pushbuttons (nPORRST and nRST)
- One SD card slot (SPI mode)
- Embedded trace macrocell (ETM) debug interface via MIPI connector
- Configurable pin mux options
- 5 V and 3.3 V analog-to-digital converter (ADC) option jumper
- Current measurement capability for 3.3 V IO, 1.2 V core, 1.2 V core, 1.2 V PLL, 3.3 V or 5 V ADC, and 3.3 V V_{CCP}
- Accepts an external power supply between +5V and +12V

1.3 HDK Board Block Diagram

Figure 1-1 illustrates the HDK block diagram.

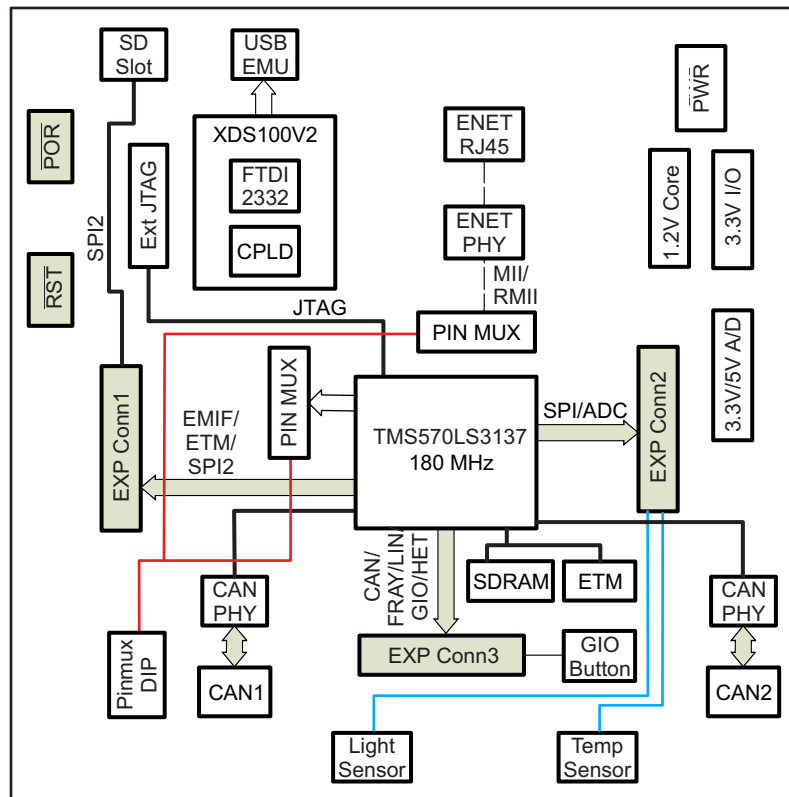


Figure 1-1. TMS570LS31 HDK Board Block Diagram

1.4 TMS570LS31 HDK Contents

The kit contains everything needed to develop and run applications for TMS570LS3137 microcontrollers including:

- Board:
 - TMS570LS31 Card
- Cables and Accessories
 - Type A to mini B USB cable for using on board XDS100V2 JTAG emulator
 - Ethernet cable
 - Flashlight for light sensor demo
- CCS DVD Containing:
 - Texas Instruments' Code Composer Studio™ Integrated Development Environments (IDE)
- Hercules DVD Containing:
 - Hercules Safety Demos
 - Hardware Abstraction Layer Code Generator (HALCoGen)
 - Training Videos
 - Device Documentation

Not included:

- 12-V power supply

Below are two options that electrically and mechanically will work with the HDK:

- [QAWA-24-12-US01](#)
 - 12-V output, 2-A max output current
 - Positive center
 - Barrel plug (2.1-mm x 5.5-mm)
 - Output Protection: Short Circuit, Overvoltage, Overcurrent
 - Safety approvals: CB, CE, UL, FCC, PSE, LPS, BSMI, RCM, and CCC
- [SMI24-12-V-P5](#)
 - 12-V output, 2-A max output current
 - Positive center
 - Barrel plug (2.1-mm x 5.5-mm)
 - Output Protection: Short Circuit, Overvoltage, Overcurrent
 - Safety approvals: UL/cUL, CCC, RCM, and PSE

1.5 HDK Specifications

- Board supply voltage: 5 V–12 V Vdc
- Board supply current: 130 mA typ (fully active, CPU at 180 MHz)
- Dimensions: 4.90" x 4.30" x 0.85" (LxWxH)

1.6 Basic Operation

The HDK is designed to work with TI's Code Composer Studio and other third party ARM IDEs. The IDE communicates with the board through the embedded emulator or an external JTAG emulator. To start, follow the instructions in the Quick Start Guide to install Hercules-specific software. This process will install all of the necessary development tools, documentation and drivers.

1.7 Memory Map

The TMS570LS31 family of MCUs have a large byte addressable address space. [Table 1-1](#) shows the address space of a TMS570LS3137 microcontroller on the left with specific details of how each region is used by the HDK on the right. By default, the internal memory sits at the beginning of the address space.

The SDRAM is mapped into CS0 space on the EMIF. CS[4:2] are used for synchronous memory for example SRAM, NOR Flash, NAND Flash, and so forth.

To use EMIF, the MPU has to be enabled, and the CS regions have to be configured as "device mode" or "strongly ordered mode" through MPU.

Table 1-1. TMS570LS31 Memory Map

Start Address	End Address	HDK
0x0000 0000	0x002F FFFF	Flash
0x0800 0000	0x0803 FFFF	RAM
0x0840 0000	0x0843 FFFF	RAM-ECC
0x6000 0000	0x63FF FFFF	CS2 Async RAM
0x6400 0000	0x67FF FFFF	CS3 Async RAM
0x6800 0000	0x7BFF FFFF	CS4 Async RAM
0x8000 0000	0x87FF FFFF	CS0 Sync SDRAM

1.8 Power Supply

The HDK board operates from a single +12 V external power supply connected to the main power input (P1), a 2.5 mm, barrel-type plug. Internally, the +12 V input is converted into +1.2 V, +3.3 V and +5.0 V using Texas Instruments swift voltage regulators and PTH power module. The +1.2 V supply is used for the MCU core while the +3.3 V supply is used for the MCU's I/O buffers and other module on the board. The +5.0 V supply is used for ADC power (second option) and USB VBUS.

There are multiple power test points on the HDK board. The three main test point pairs provide a convenient mechanism to check the HDK's current for each supply. [Table 1-2](#) shows the voltages for each test point and what the supply is used for.

Table 1-2. Power Test Points

Test Point Pair	Voltage	Voltage Use
TP14 and TP15	1.2 V	MCU core
TP16 and TP17	3.3 V	MCU IO and logic
TP18 and TP19	1.2 V	MCU PLL
TP20 and TP21	3.3 V	MCU Flash pump
TP22 and TP23	3.3 V or 5.0 V (J8 to enable 5 V)	MCU MibADC, and ADREFHI

Physical Description

This section describes the physical layout of the TMS570LS31 HDK board and its interfaces.

2.1 Board Layout

The TMS570LS31 HDK board is a 4.9 x 4.3 inch (125 x 109 mm) eight layer printed circuit board that is powered by an external +5 V to approximately +12 V only power supply. [Figure 2-1](#) shows the layout of the TMS570LS31 HDK board.



Figure 2-1. TMS570LS31 HDK Board, Interfaces Top Side

2.2 Connectors

The HDK board has 13 interfaces to various peripherals. These interfaces are described in the following sections.

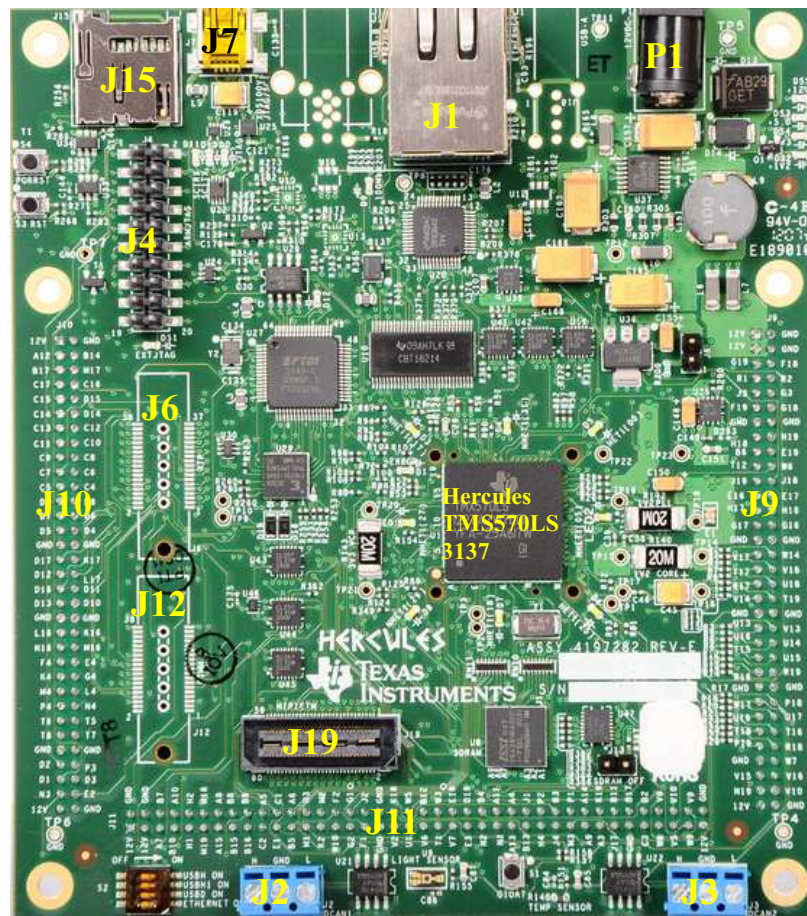


Figure 2-2. Connectors on TMS570LS31 HDK

Table 2-1. Connectors on HDK Board

Connector	Size	Function
J1	RJ45	Ethernet
J2	3 terminal, 2.54mm	DCAN1
J3	3 terminal, 2.54mm	DCAN2
J4	10x2, 2.54mm	ARM 20pin JTAG header
J6	19x2, mictor	RTP
J7	4pin, Mini-B USB	XDS100V2 USB
J9	33x2, 2mm	Exp P1, SPI1, SPI5, ADC
J10	33x2, 2mm	EXP P2, SPI2, EMIF, ECLK
J11	40x2, 2mm	EXP P3, SPI3, GIO, NHET, DCAN, LIN
J12	19x2, mictor	DMM
J15		SD card
J19	30x2, MIPI	ETM MIPI Header
P1	2.5mm	+12 V In

2.2.1 20-Pin ARM JTAG Header

In addition to on board XDS100V2 JTAG, one 20-pin ARM JTAG header is added for using external emulator. This is the standard interface used by JTAG emulators to interface to ARM microcontrollers. The pinout for the connector is shown in [Table 2-2](#).

Table 2-2. 20-Pin ARM JTAG Header

Signal Name	Pin Number	Pin Number	Signal Name
Vref	1	2	V _{CC}
nTRST	3	4	GND
TDI	5	6	GND
TMS	7	8	GND
TCK	9	10	GND
RTCK	11	12	GND
TDO	13	14	GND
nRST	15	16	GND
NC	17	18	GND
NC	19	20	GND

2.2.2 Ethernet Interface

The TMS570LS3137 integrates an MII/RMII Ethernet MAC on chip. This interface is routed to the on board PHY via CBT switches. The board uses a DP83640 PHY. The interface is isolated and brought out to a RJ-45 connector with integrated magnetics, J1. The pinmux control DIP S2 is used to control the CBT FET switch for RMII, MII or other functions.

The J1 connector is used to provide a 10/100 Mbps Ethernet interface. This is a standard RJ-45 connector. The cable end pinout for the J1 connector is shown in [Table 2-3](#).

Table 2-3. J1, Ethernet Interface

Pin Number	Signal	Pin Number	Signal
1	D0+	2	D0-
3	D1-	4	D2+
5	D2-	6	D1-
7	D3+	8	D3-

Two LEDs are embedded into the connector to report link status (green LED) and transmit and receive status of the PHY (yellow LED).

2.2.3 CAN Interface

The TMS570LS3137 has up to three DCAN interfaces that provide a high-speed serial interface. Two 3-pin screw terminal blocks, J2, J3, are used to interface to the DCAN bus. The pinouts for this connector are shown in [Figure 2-4](#). H means CAN High (CAN H), and L means CAN Low (CAN L).

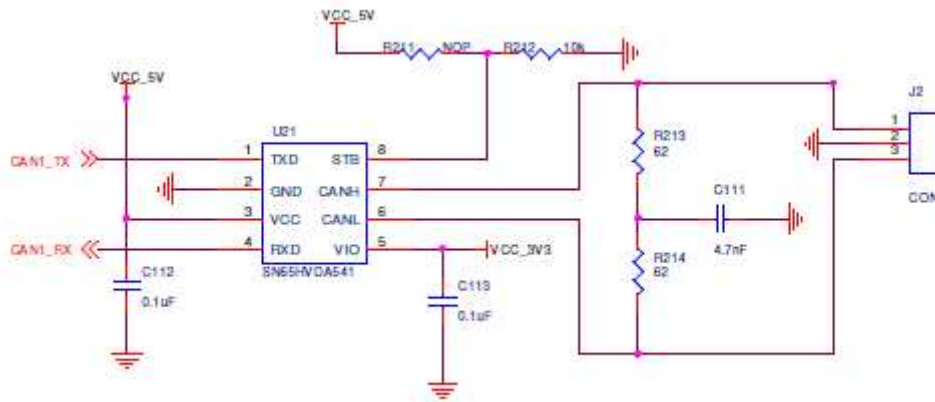


Figure 2-3. CAN Bus Termination

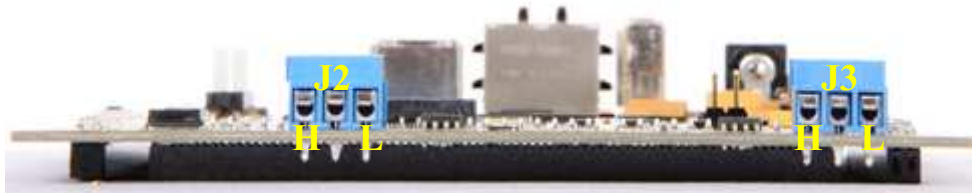


Figure 2-4. J2, J3 CAN Bus Interface (Screw Terminal)

2.2.4 J19, MIPI ETM Connector

Figure 2-5 and Table 2-4 show the 60 pin MIPI header.

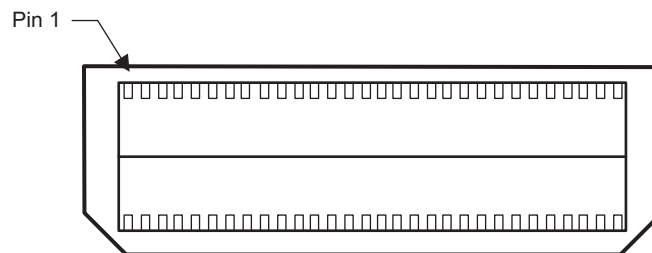


Figure 2-5. J19, 60 Pin MIPI ETM Header

Table 2-4. J19, MIPI Connector Signal Mapping

MCU Signals	Pin Number	Pin Number	MCU Signals
3.3V	1	2	TMS
TCK	3	4	TDO
TDI	5	6	System reset
RTCK	7	8	nTRST
NC	9	10	NC
NC	11	12	3.3 V
ETMTACECLKOUT	13	14	NC
To GND thru 0 W	15	16	GND
EMTTRACECTL	17	18	ETMDATA[19]
ETMDATA[0]	19	20	ETMDATA[20]
ETMDATA[1]	21	22	ETMDATA[21]
ETMDATA[2]	23	24	ETMDATA[22]
ETMDATA[3]	25	26	ETMDATA[23]
ETMDATA[4]	27	28	ETMDATA[24]
ETMDATA[5]	29	30	ETMDATA[25]
ETMDATA[6]	31	32	ETMDATA[26]
ETMDATA[7]	33	34	ETMDATA[27]
ETMDATA[8]	35	36	ETMDATA[28]
ETMDATA[9]	37	38	ETMDATA[29]
ETMDATA[10]	39	40	ETMDATA[30]
ETMDATA[11]	41	42	ETMDATA[31]
ETMDATA[12]	43	44	NC
ETMDATA[13]	45	46	NC
ETMDATA[14]	47	48	NC
ETMDATA[15]	49	50	NC
ETMDATA[16]	51	52	NC
ETMDATA[17]	53	54	NC
ETMDATA[18]	55	56	NC
GND	57	58	GND
NC	59	60	NC

2.2.5 J7, XDS100V2 USB JTAG Interface

The USB connector J7 is used to connect to the host development system that is running the software development IDE, Code Composer Studio. The signals on this connector are shown in [Table 2-5](#).

Table 2-5. J7, XDS100V2 USB JTAG Interface

Pin Number	Signal Name
1	USBVDD
2	D-
3	D+
4	NC
5	USBVSS

Before the board is shipped, the XDS100V2 port1 is configured as JTAG, and port2 is configured as SCI. The CPLD on the board is also programmed to route the JTAG signals to the MCU.

There is a circuitry to detect the external JTAG emulator. If a device is plugged onto the header J4 and J19, the DS1 LED will be turned on, and XDS100V2 JTAG is disabled.

2.2.6 P1, +5 V to +12 V Input

Connector P1 is the input power connector. This connector brings in +5 V to +12 V to the HDK board. This is a 2.5 mm jack. [Figure 2-6](#) shows this connector as viewed from the card edge.

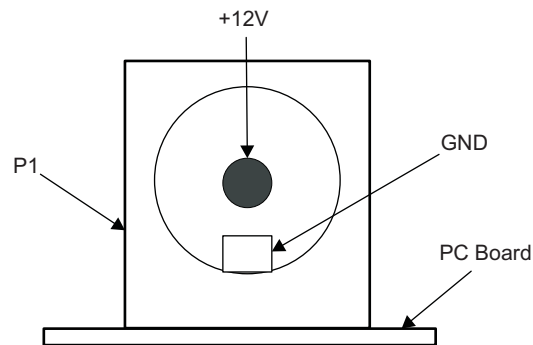


Figure 2-6. +12 V Input Jack

2.2.7 SCI Interface

The internal SCI on the TMS570LS3137 device is connected to the second port of the XDS100V2. The XDS100V2 USB driver makes the FT2232H second channel appear as a virtual COM port (VCP). This allows the user to communicate with the USB interface via a standard PC serial emulation port.

2.2.8 Daughter Card Interface

The HDK provides expansion connectors that can be used to accept plug-in daughter cards. The daughter card allows users to build on their EVM platform to extend its capabilities and provide customer and application specific I/O. The expansion connectors are for all major interfaces including asynchronous memory, peripherals, and A/D expansion.

There are three daughter card interfaces: J9, J10, J11. These connectors are described in [Table 2-6](#).

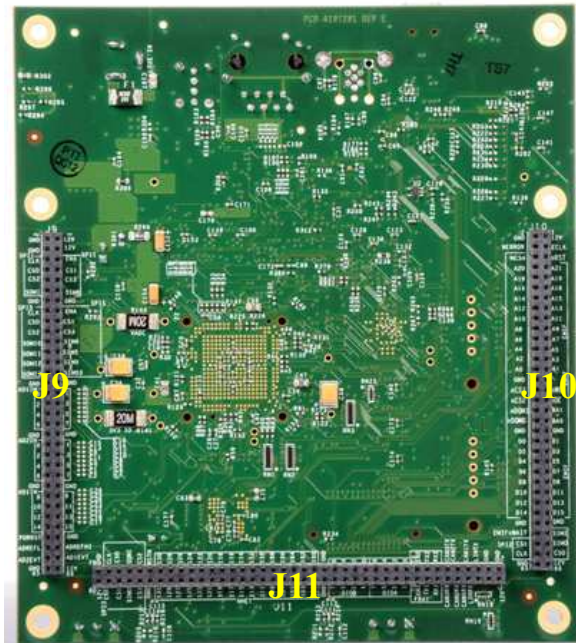


Figure 2-7. J9, J10, and J11 on HDK

Table 2-6. Expansion Connector P1 (J9, Left, BottomView)

Signal Name	Pin Number	Number	Pin Number	Signal Name	
EXP_12V		1	2	GND	
EXP_12V		3	4	GND	
MibSPI1ENA	G19	5	6	F18	MibSPI1CLK
MibSPI1CS[1]	F3	7	8	R2	MibSPI1CS[0]
MibSPI1CS[3]	J3	9	10	G3	MibSPI1CS[2]
MibSPI1SIMO	F19	11	12	G18	MibSPI1SOMI
GND		13	14		GND
MibSPI5ENA	H18	15	16	H19	MibSPI5CLK
MibSPI5CS[1]	B6	17	18	E19	MibSPI5CS[0]
MibSPI5CS[3]	T12	19	20	W6	MibSPI5CS[2]
MibSPI5SIMO[0]	J19	21	22		MibSPI5SOMI[0]
MibSPI5SIMO[1]	E16	23	24	E17	MibSPI5SOMI[1]
MibSPI5SIMO[2]	H17	25	26	H16	MibSPI5SOMI[2]
MibSPI5SIMO[3]	G17	27	28	G16	MibSPI5SOMI[3]
GND		29	30		GND
AD1IN[1]	V17	31	32	W14	AD1IN[0]
AD1IN[3]	T17	33	34	V18	AD1IN[2]
AD1IN[5]	R17	35	36	U18	AD1IN[4]
AD1IN[7]	V14	37	38	T19	AD1IN[6]
GND		39	40		GND
AD2IN[1]	U13	41	42	V13	AD2IN[0]
AD2IN[3]	U16	43	44	U14	AD2IN[2]
AD2IN[5]	T15	45	46	U15	AD2IN[4]
AD2IN[7]	R16	47	48	R19	AD2IN[6]
AGND		49	50		GND

Table 2-6. Expansion Connector P1 (J9, Left, BottomView) (continued)

Signal Name	Pin Number	Number	Pin Number	Signal Name	
AD1IN[9]	W17	51	52	P18	AD1IN[8]
AD1IN[11]	U19	53	54	U17	AD1IN[10]
AD1IN[13]	T18	55	56	T16	AD1IN[12]
AD1IN[15]	P19	57	58	R18	AD1IN[14]
GND		59	60		POR_RSTn
ADREFHI	V15	61	62	V16	ADREFLO
AD1EVT	N19	63	64	V10	AD2EVT
EXP_12V		65	66		GND

Table 2-7. Expansion Connector P2 (J10, Right, BottomView)

Signal Name	Pin Number	Number	Pin Number	Signal Name	
EXP_12V		1	2	GND	
ECLK	A12	3	4	B14	ERRORn
RST		5	6	M17	EMIF_CS[4]
NC	C17	7	8	C16	NC
NC	C15	9	10	D15	NC
NC	C14	11	12	D14	NC
NC	C13	13	14	C12	NC
NC	C11	15	16	C10	EMIF_ADDR[12]
EMIF_ADDR[11]	C9	17	18	C8	EMIF_ADDR[10]
EMIF_ADDR[9]	C7	19	20	C6	EMIF_ADDR[8]
EMIF_ADDR[7]	C5	21	22	C4	EMIF_ADDR[6]
EMIF_ADDR[5]	D9	23	24	D8	EMIF_ADDR[4]
EMIF_ADDR[3]	D7	25	26	D6	EMIF_ADDR[2]
EMIF_ADDR[1]	D5	27	28	D4	EMIF_ADDR[0]
GND		29	30		GND
EMIF_Wen	D17	31	32	K17	EMIF_CS[3]
EMIF_Oen	D12	33	34	L17	EMIF_CS[2]
EMIF_BA[1]	D16	35	36	D11	EMIF_DQMn[1]
EMIF_BA[0]	D13	37	38	D10	EMIF_DQMn[0]
GND		39	40		GND
EMIFDATA[1]	L16	41	42	K16	EMIFDATA[0]
EMIFDATA[3]	N16	43	44	M16	EMIFDATA[2]
EMIFDATA[5]	F4	45	46	E4	EMIFDATA[4]
EMIFDATA[7]	K4	47	48	G4	EMIFDATA[6]
EMIFDATA[9]	M4	49	50	L4	EMIFDATA[8]
EMIFDATA[11]	P4	51	52	N4	EMIFDATA[10]
EMIFDATA[13]	T6	53	54	T5	EMIFDATA[12]
EMIFDATA[15]	T8	55	56	T7	EMIFDATA[14]
GND		57	58		GND
SPI2_SOMI	D2	59	60	P3	EMIF_nWAIT
SPI2_SIMO	D1	61	62	D3	SPI2_CS1
SPI2_CS0	N3	63	64	E2	SPI2_CLK
EXP_12V		65	66		GND

Table 2-8. Expansion Connector P3 (J11, Bottom One, TopView)

Signal Name	Pin Number	Number	Pin Number	Signal Name	
EXP_12V		1	2	GND	
EXP_12V		3	4	GND	
LINRX	A7	5	6	B7	LINTX
CAN1RX	B10	7	8	A10	CAN1TX
CAN2RX	H1	9	10	H2	CAN2TX
CAN3RX	M19	11	12	M18	CAN3TX
FRAYRX1	A15	13	14	A8	FRAYRX2
FRAYTX1	B15	15	16	B8	FRAYTX2
FRAYTXEN1	B16	17	18	B9	FRAYTXEN2
GIOA[1]	C2	19	20	A5	GIOA[0]
GIOA[3]	E1	21	22	C1	GIOA[2]
GIOA[5]	B5	23	24	A6	GIOA[4]
GIOA[7]	M1	25	26	H3	GIOA[6]
GIOB[1]	K2	27	28	M2	GIOB[0]
GIOB[3]	W10	29	30	F2	GIOB[2]
GIOB[5]	G2	31	32	G1	GIOB[4]
GIOB[7]	F1	33	34	J2	GIOB[6]
GND		35	36		GND
NHET1[1]	V2	37	38	K18	NHET1[0]
NHET1[3]	U1	39	40	W5	NHET1[2]
NHET1[5]	V6	41	42	B12	NHET1[4]
NHET1[7]	T1	43	44	W3	NHET1[6]
NHET1[9]	V7	45	46	E18	NHET1[8]
NHET1[11]	E3	47	48	D19	NHET1[10]
NHET1[13]	N2	49	50	B4	NHET1[12]
NHET1[15]	N1	51	52	A11	NHET1[14]
NHET1[17]	A13	53	54	A4	NHET1[16]
NHET1[19]	B13	55	56	J1	NHET1[18]
NHET1[21]	H4	57	58	P2	NHET1[20]
NHET1[23]	J4	59	60	B3	NHET1[22]
NHET1[25]	M3	61	62	P1	NHET1[24]
NHET1[27]	A9	63	64	A14	NHET1[26]
NHET1[29]	A3	65	66	K19	NHET1[28]
NHET1[31]	J17	67	68	B11	NHET1[30]
GND		69	70		GND
MibSPI3CS[3]	C3	71	72	B2	MibSPI3CS[2]
MibSPI3SIMO	W8	73	74	V8	MibSPI3SOMI
MibSPI3CS[1]	V5	75	76	V10	MibSPI3CS[0]
MibSPI3ENA	W9	77	78	V9	MibSPI3CLK
EXP_12V		79	80		GND

2.3 LEDs

The TMS570LS31 HDK board has 19 LEDs. Eight of these LEDs (shown in [Table 2-9](#)) are under user control. Those LEDs are controlled and programmed by NHET signals.

LEDs DS2, DS3, DS4, and DS5 indicate the presence of the power (+1.2 V, +5 V, 3.3 V, and 12 V) s on the board. The LED functions are summarized in [Table 2-9](#) and [Table 2-10](#).

Table 2-9. Demo LEDs

LED Number	Location	Signals	Color
D3	Left Top	NHET1[17]	White
D4	Top	NHET1[31]	White
D5	Right Top	NHET1[0]	White
D6	Right Bottom	NHET1[25]	White
D7	Bottom	NHET1[18]	White
D8	Left bottom	NHET1[29]	White
LED1	Left	NHET1[27]	White
LED2	Right	NHET1[05]	White

Table 2-10. Other LEDs as Indicator

Number	LED	Color
D1	nERROR	Red
D10	XDS100V2 SCI RX	Blue
D11	XDS100V2 SCI TX	Blue
D12	XDS100V2 PWRENn	Blue
D2	JTAG TDI	Blue
D9	Ethernet Speed	Blue
DS1	ARM JTAG Plugin	Blue
DS2	VCC_1V2	Blue
DS3	VCC_5V	Blue
DS4	VCC_3V3	Blue
DS5	VCC_12V	Blue

2.4 S2 DIP Switch

There is one 4-position DIP switches located on the left-bottom corner at reference designator S2. By default, all of the switches are set to the “OFF” position and should remain in that position when completing the steps in this user’s guide.

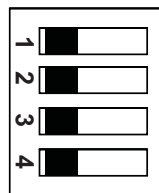


Figure 2-8. DIP Switch Settings

The S2 DIP switch is reserved for user application general purpose. [Table 2-11](#) describes the function of each channel on S2.

Table 2-11. S2 DIP Switch Functions

Switch	OFF Position	ON Position
S2:1 ⁽¹⁾	USB Host0 Disabled	USB Host0 Enabled
S2:2 ⁽²⁾	USB Host1 Disabled	USB Host1 Enabled
S2:3 ⁽²⁾	USB Device Disabled	USB Device Enabled
S2:4 ⁽³⁾	Ethernet Disabled	Ethernet Enabled

⁽¹⁾ S2:1 indicates slide 1 on the S2 DIP switch, S2:2 indicates slide 2 on the S2 DIP switch, and so on.

⁽²⁾ S2:2 and S2:3 cannot be enabled at the same time since those two ports have pinmux.

⁽³⁾ To use Ethernet, S2:4 should be enabled and all other have to be disabled.

2.5 Jumpers

The HDK board has two jumpers that are used to enable and disable the on-board SDRAM and select 5 V or 3.3 V ADC.

Table 2-12. Jumpers

Jumper Number	OFF	ON
J8	5 V ADC	3.3 V ADC
J13	SDRAM on	SDRAM Off

2.6 S4, Power On Reset Switch

TMS570LS31 MCU has two resets: warm reset (nRST) and power-on reset (nPORRST). Switch S4 is a momentary switch that asserts power on reset to the TMS570LS3137 device. The nPORRST condition is intended to reset all logic on the device including the test and emulation circuitry.

2.7 S3, System Reset Switch

Switch S3 is used to assert a warm reset the TMS570LS3137 device. Warm reset does not reset any test or emulation logic. The reset signal from window watchdog will also assert a warm reset to the MCU. The warm reset can be invoked by pushing nRST button, or by RESET signals from XDS100 CPLD, ARM JTAG SREST.

Operation Notices

A.1 Operation Notices

The user assumes all responsibility and liability for proper and safe handling of the boards. It is the user's responsibility to take any and all appropriate precautions with regard to electrostatic discharge.

- For additional information regarding the embedded emulation, see the XDS100 USB wiki on the TI web site at the following URL: <http://tiexpressdsp.com/index.php?title=XDS100>
- Code Composer Studio support is available via a forum at: <http://community.ti.com/forums/138.aspx>
- Hercules MCU support is available via a forum at: <http://www.ti.com/hercules-support>



Revision History

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

Changes from B Revision (September 2013) to C Revision	Page
• Updated TMS570LS31 HDK Contents power supply information.	6

STANDARD TERMS FOR EVALUATION MODULES

1. *Delivery:* TI delivers TI evaluation boards, kits, or modules, including any accompanying demonstration software, components, and/or documentation which may be provided together or separately (collectively, an "EVM" or "EVMs") to the User ("User") in accordance with the terms set forth herein. User's acceptance of the EVM is expressly subject to the following terms.
 - 1.1 EVMs are intended solely for product or software developers for use in a research and development setting to facilitate feasibility evaluation, experimentation, or scientific analysis of TI semiconductor products. EVMs have no direct function and are not finished products. EVMs shall not be directly or indirectly assembled as a part or subassembly in any finished product. For clarification, any software or software tools provided with the EVM ("Software") shall not be subject to the terms and conditions set forth herein but rather shall be subject to the applicable terms that accompany such Software
 - 1.2 EVMs are not intended for consumer or household use. EVMs may not be sold, sublicensed, leased, rented, loaned, assigned, or otherwise distributed for commercial purposes by Users, in whole or in part, or used in any finished product or production system.
2. *Limited Warranty and Related Remedies/Disclaimers:*
 - 2.1 These terms do not apply to Software. The warranty, if any, for Software is covered in the applicable Software License Agreement.
 - 2.2 TI warrants that the TI EVM will conform to TI's published specifications for ninety (90) days after the date TI delivers such EVM to User. Notwithstanding the foregoing, TI shall not be liable for a nonconforming EVM if (a) the nonconformity was caused by neglect, misuse or mistreatment by an entity other than TI, including improper installation or testing, or for any EVMs that have been altered or modified in any way by an entity other than TI, (b) the nonconformity resulted from User's design, specifications or instructions for such EVMs or improper system design, or (c) User has not paid on time. Testing and other quality control techniques are used to the extent TI deems necessary. TI does not test all parameters of each EVM. User's claims against TI under this Section 2 are void if User fails to notify TI of any apparent defects in the EVMs within ten (10) business days after delivery, or of any hidden defects with ten (10) business days after the defect has been detected.
 - 2.3 TI's sole liability shall be at its option to repair or replace EVMs that fail to conform to the warranty set forth above, or credit User's account for such EVM. TI's liability under this warranty shall be limited to EVMs that are returned during the warranty period to the address designated by TI and that are determined by TI not to conform to such warranty. If TI elects to repair or replace such EVM, TI shall have a reasonable time to repair such EVM or provide replacements. Repaired EVMs shall be warranted for the remainder of the original warranty period. Replaced EVMs shall be warranted for a new full ninety (90) day warranty period.
3. *Regulatory Notices:*
 - 3.1 *United States*
 - 3.1.1 *Notice applicable to EVMs not FCC-Approved:*

FCC NOTICE: This kit is designed to allow product developers to evaluate electronic components, circuitry, or software associated with the kit to determine whether to incorporate such items in a finished product and software developers to write software applications for use with the end product. This kit is not a finished product and when assembled may not be resold or otherwise marketed unless all required FCC equipment authorizations are first obtained. Operation is subject to the condition that this product not cause harmful interference to licensed radio stations and that this product accept harmful interference. Unless the assembled kit is designed to operate under part 15, part 18 or part 95 of this chapter, the operator of the kit must operate under the authority of an FCC license holder or must secure an experimental authorization under part 5 of this chapter.
 - 3.1.2 *For EVMs annotated as FCC – FEDERAL COMMUNICATIONS COMMISSION Part 15 Compliant:*

CAUTION

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions: (1) This device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

Changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment.

FCC Interference Statement for Class A EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class A digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference when the equipment is operated in a commercial environment. This equipment generates, uses, and can radiate radio frequency energy and, if not installed and used in accordance with the instruction manual, may cause harmful interference to radio communications. Operation of this equipment in a residential area is likely to cause harmful interference in which case the user will be required to correct the interference at his own expense.

FCC Interference Statement for Class B EVM devices

NOTE: This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

3.2 Canada

3.2.1 For EVMs issued with an Industry Canada Certificate of Conformance to RSS-210 or RSS-247

Concerning EVMs Including Radio Transmitters:

This device complies with Industry Canada license-exempt RSSs. Operation is subject to the following two conditions:

(1) this device may not cause interference, and (2) this device must accept any interference, including interference that may cause undesired operation of the device.

Concernant les EVMs avec appareils radio:

Le présent appareil est conforme aux CNR d'Industrie Canada applicables aux appareils radio exempts de licence. L'exploitation est autorisée aux deux conditions suivantes: (1) l'appareil ne doit pas produire de brouillage, et (2) l'utilisateur de l'appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d'en compromettre le fonctionnement.

Concerning EVMs Including Detachable Antennas:

Under Industry Canada regulations, this radio transmitter may only operate using an antenna of a type and maximum (or lesser) gain approved for the transmitter by Industry Canada. To reduce potential radio interference to other users, the antenna type and its gain should be so chosen that the equivalent isotropically radiated power (e.i.r.p.) is not more than that necessary for successful communication. This radio transmitter has been approved by Industry Canada to operate with the antenna types listed in the user guide with the maximum permissible gain and required antenna impedance for each antenna type indicated. Antenna types not included in this list, having a gain greater than the maximum gain indicated for that type, are strictly prohibited for use with this device.

Concernant les EVMs avec antennes détachables

Conformément à la réglementation d'Industrie Canada, le présent émetteur radio peut fonctionner avec une antenne d'un type et d'un gain maximal (ou inférieur) approuvé pour l'émetteur par Industrie Canada. Dans le but de réduire les risques de brouillage radioélectrique à l'intention des autres utilisateurs, il faut choisir le type d'antenne et son gain de sorte que la puissance isotrope rayonnée équivalente (p.i.r.e.) ne dépasse pas l'intensité nécessaire à l'établissement d'une communication satisfaisante. Le présent émetteur radio a été approuvé par Industrie Canada pour fonctionner avec les types d'antenne énumérés dans le manuel d'usage et ayant un gain admissible maximal et l'impédance requise pour chaque type d'antenne. Les types d'antenne non inclus dans cette liste, ou dont le gain est supérieur au gain maximal indiqué, sont strictement interdits pour l'exploitation de l'émetteur.

3.3 Japan

3.3.1 *Notice for EVMs delivered in Japan:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page 日本国内に輸入される評価用キット、ボードについては、次のところをご覧ください。
http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_01.page

3.3.2 *Notice for Users of EVMs Considered "Radio Frequency Products" in Japan:* EVMs entering Japan may not be certified by TI as conforming to Technical Regulations of Radio Law of Japan.

If User uses EVMs in Japan, not certified to Technical Regulations of Radio Law of Japan, User is required to follow the instructions set forth by Radio Law of Japan, which includes, but is not limited to, the instructions below with respect to EVMs (which for the avoidance of doubt are stated strictly for convenience and should be verified by User):

1. Use EVMs in a shielded room or any other test facility as defined in the notification #173 issued by Ministry of Internal Affairs and Communications on March 28, 2006, based on Sub-section 1.1 of Article 6 of the Ministry's Rule for Enforcement of Radio Law of Japan,
2. Use EVMs only after User obtains the license of Test Radio Station as provided in Radio Law of Japan with respect to EVMs, or
3. Use of EVMs only after User obtains the Technical Regulations Conformity Certification as provided in Radio Law of Japan with respect to EVMs. Also, do not transfer EVMs, unless User gives the same notice above to the transferee. Please note that if User does not follow the instructions above, User will be subject to penalties of Radio Law of Japan.

【無線電波を送信する製品の開発キットをお使いになる際の注意事項】 開発キットの中には技術基準適合証明を受けていないものがあります。技術適合証明を受けていないものご使用に際しては、電波法遵守のため、以下のいずれかの措置を取っていただく必要がありますのでご注意ください。

1. 電波法施行規則第6条第1項第1号に基づく平成18年3月28日総務省告示第173号で定められた電波暗室等の試験設備でご使用いただく。
2. 実験局の免許を取得後ご使用いただく。
3. 技術基準適合証明を取得後ご使用いただく。

なお、本製品は、上記の「ご使用にあたっての注意」を譲渡先、移転先に通知しない限り、譲渡、移転できないものとします。

上記を遵守頂けない場合は、電波法の罰則が適用される可能性があることをご留意ください。日本テキサス・インスツルメンツ株式会社
東京都新宿区西新宿 6 丁目 2 4 番 1 号
西新宿三井ビル

3.3.3 *Notice for EVMs for Power Line Communication:* Please see http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page
電力線搬送波通信についての開発キットをお使いになる際の注意事項については、次のところをご覧ください。 http://www.tij.co.jp/lstds/ti_ja/general/eStore/notice_02.page

3.4 *European Union*

3.4.1 *For EVMs subject to EU Directive 2014/30/EU (Electromagnetic Compatibility Directive):*

This is a class A product intended for use in environments other than domestic environments that are connected to a low-voltage power-supply network that supplies buildings used for domestic purposes. In a domestic environment this product may cause radio interference in which case the user may be required to take adequate measures.

4 *EVM Use Restrictions and Warnings:*

4.1 EVMS ARE NOT FOR USE IN FUNCTIONAL SAFETY AND/OR SAFETY CRITICAL EVALUATIONS, INCLUDING BUT NOT LIMITED TO EVALUATIONS OF LIFE SUPPORT APPLICATIONS.

4.2 User must read and apply the user guide and other available documentation provided by TI regarding the EVM prior to handling or using the EVM, including without limitation any warning or restriction notices. The notices contain important safety information related to, for example, temperatures and voltages.

4.3 *Safety-Related Warnings and Restrictions:*

4.3.1 User shall operate the EVM within TI's recommended specifications and environmental considerations stated in the user guide, other available documentation provided by TI, and any other applicable requirements and employ reasonable and customary safeguards. Exceeding the specified performance ratings and specifications (including but not limited to input and output voltage, current, power, and environmental ranges) for the EVM may cause personal injury or death, or property damage. If there are questions concerning performance ratings and specifications, User should contact a TI field representative prior to connecting interface electronics including input power and intended loads. Any loads applied outside of the specified output range may also result in unintended and/or inaccurate operation and/or possible permanent damage to the EVM and/or interface electronics. Please consult the EVM user guide prior to connecting any load to the EVM output. If there is uncertainty as to the load specification, please contact a TI field representative. During normal operation, even with the inputs and outputs kept within the specified allowable ranges, some circuit components may have elevated case temperatures. These components include but are not limited to linear regulators, switching transistors, pass transistors, current sense resistors, and heat sinks, which can be identified using the information in the associated documentation. When working with the EVM, please be aware that the EVM may become very warm.

4.3.2 EVMs are intended solely for use by technically qualified, professional electronics experts who are familiar with the dangers and application risks associated with handling electrical mechanical components, systems, and subsystems. User assumes all responsibility and liability for proper and safe handling and use of the EVM by User or its employees, affiliates, contractors or designees. User assumes all responsibility and liability to ensure that any interfaces (electronic and/or mechanical) between the EVM and any human body are designed with suitable isolation and means to safely limit accessible leakage currents to minimize the risk of electrical shock hazard. User assumes all responsibility and liability for any improper or unsafe handling or use of the EVM by User or its employees, affiliates, contractors or designees.

4.4 User assumes all responsibility and liability to determine whether the EVM is subject to any applicable international, federal, state, or local laws and regulations related to User's handling and use of the EVM and, if applicable, User assumes all responsibility and liability for compliance in all respects with such laws and regulations. User assumes all responsibility and liability for proper disposal and recycling of the EVM consistent with all applicable international, federal, state, and local requirements.

5. *Accuracy of Information:* To the extent TI provides information on the availability and function of EVMs, TI attempts to be as accurate as possible. However, TI does not warrant the accuracy of EVM descriptions, EVM availability or other information on its websites as accurate, complete, reliable, current, or error-free.

6. *Disclaimers:*
- 6.1 EXCEPT AS SET FORTH ABOVE, EVMS AND ANY MATERIALS PROVIDED WITH THE EVM (INCLUDING, BUT NOT LIMITED TO, REFERENCE DESIGNS AND THE DESIGN OF THE EVM ITSELF) ARE PROVIDED "AS IS" AND "WITH ALL FAULTS." TI DISCLAIMS ALL OTHER WARRANTIES, EXPRESS OR IMPLIED, REGARDING SUCH ITEMS, INCLUDING BUT NOT LIMITED TO ANY EPIDEMIC FAILURE WARRANTY OR IMPLIED WARRANTIES OF MERCHANTABILITY OR FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF ANY THIRD PARTY PATENTS, COPYRIGHTS, TRADE SECRETS OR OTHER INTELLECTUAL PROPERTY RIGHTS.
- 6.2 EXCEPT FOR THE LIMITED RIGHT TO USE THE EVM SET FORTH HEREIN, NOTHING IN THESE TERMS SHALL BE CONSTRUED AS GRANTING OR CONFERRING ANY RIGHTS BY LICENSE, PATENT, OR ANY OTHER INDUSTRIAL OR INTELLECTUAL PROPERTY RIGHT OF TI, ITS SUPPLIERS/LICENSORS OR ANY OTHER THIRD PARTY, TO USE THE EVM IN ANY FINISHED END-USER OR READY-TO-USE FINAL PRODUCT, OR FOR ANY INVENTION, DISCOVERY OR IMPROVEMENT, REGARDLESS OF WHEN MADE, CONCEIVED OR ACQUIRED.
7. *USER'S INDEMNITY OBLIGATIONS AND REPRESENTATIONS.* USER WILL DEFEND, INDEMNIFY AND HOLD TI, ITS LICENSORS AND THEIR REPRESENTATIVES HARMLESS FROM AND AGAINST ANY AND ALL CLAIMS, DAMAGES, LOSSES, EXPENSES, COSTS AND LIABILITIES (COLLECTIVELY, "CLAIMS") ARISING OUT OF OR IN CONNECTION WITH ANY HANDLING OR USE OF THE EVM THAT IS NOT IN ACCORDANCE WITH THESE TERMS. THIS OBLIGATION SHALL APPLY WHETHER CLAIMS ARISE UNDER STATUTE, REGULATION, OR THE LAW OF TORT, CONTRACT OR ANY OTHER LEGAL THEORY, AND EVEN IF THE EVM FAILS TO PERFORM AS DESCRIBED OR EXPECTED.
8. *Limitations on Damages and Liability:*
- 8.1 *General Limitations.* IN NO EVENT SHALL TI BE LIABLE FOR ANY SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL, OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF THESE TERMS OR THE USE OF THE EVMS , REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. EXCLUDED DAMAGES INCLUDE, BUT ARE NOT LIMITED TO, COST OF REMOVAL OR REINSTALLATION, ANCILLARY COSTS TO THE PROCUREMENT OF SUBSTITUTE GOODS OR SERVICES, RETESTING, OUTSIDE COMPUTER TIME, LABOR COSTS, LOSS OF GOODWILL, LOSS OF PROFITS, LOSS OF SAVINGS, LOSS OF USE, LOSS OF DATA, OR BUSINESS INTERRUPTION. NO CLAIM, SUIT OR ACTION SHALL BE BROUGHT AGAINST TI MORE THAN TWELVE (12) MONTHS AFTER THE EVENT THAT GAVE RISE TO THE CAUSE OF ACTION HAS OCCURRED.
- 8.2 *Specific Limitations.* IN NO EVENT SHALL TI'S AGGREGATE LIABILITY FROM ANY USE OF AN EVM PROVIDED HEREUNDER, INCLUDING FROM ANY WARRANTY, INDEMNITY OR OTHER OBLIGATION ARISING OUT OF OR IN CONNECTION WITH THESE TERMS, , EXCEED THE TOTAL AMOUNT PAID TO TI BY USER FOR THE PARTICULAR EVM(S) AT ISSUE DURING THE PRIOR TWELVE (12) MONTHS WITH RESPECT TO WHICH LOSSES OR DAMAGES ARE CLAIMED. THE EXISTENCE OF MORE THAN ONE CLAIM SHALL NOT ENLARGE OR EXTEND THIS LIMIT.
9. *Return Policy.* Except as otherwise provided, TI does not offer any refunds, returns, or exchanges. Furthermore, no return of EVM(s) will be accepted if the package has been opened and no return of the EVM(s) will be accepted if they are damaged or otherwise not in a resalable condition. If User feels it has been incorrectly charged for the EVM(s) it ordered or that delivery violates the applicable order, User should contact TI. All refunds will be made in full within thirty (30) working days from the return of the components(s), excluding any postage or packaging costs.
10. *Governing Law:* These terms and conditions shall be governed by and interpreted in accordance with the laws of the State of Texas, without reference to conflict-of-laws principles. User agrees that non-exclusive jurisdiction for any dispute arising out of or relating to these terms and conditions lies within courts located in the State of Texas and consents to venue in Dallas County, Texas. Notwithstanding the foregoing, any judgment may be enforced in any United States or foreign court, and TI may seek injunctive relief in any United States or foreign court.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2018, Texas Instruments Incorporated

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

 [View TMDS570LS31HDK on WIN SOURCE](#)

 [Texas Instruments](#) Information

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management